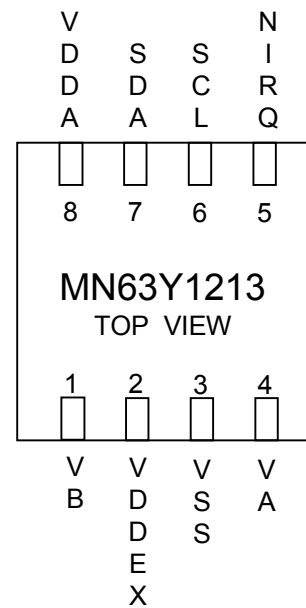
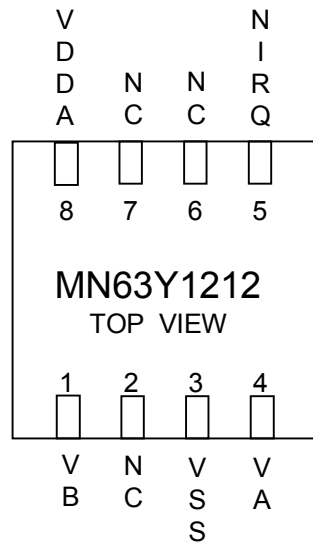


**Evaluation board circuit diagram  
and implementation  
MN63Y1212/1213**

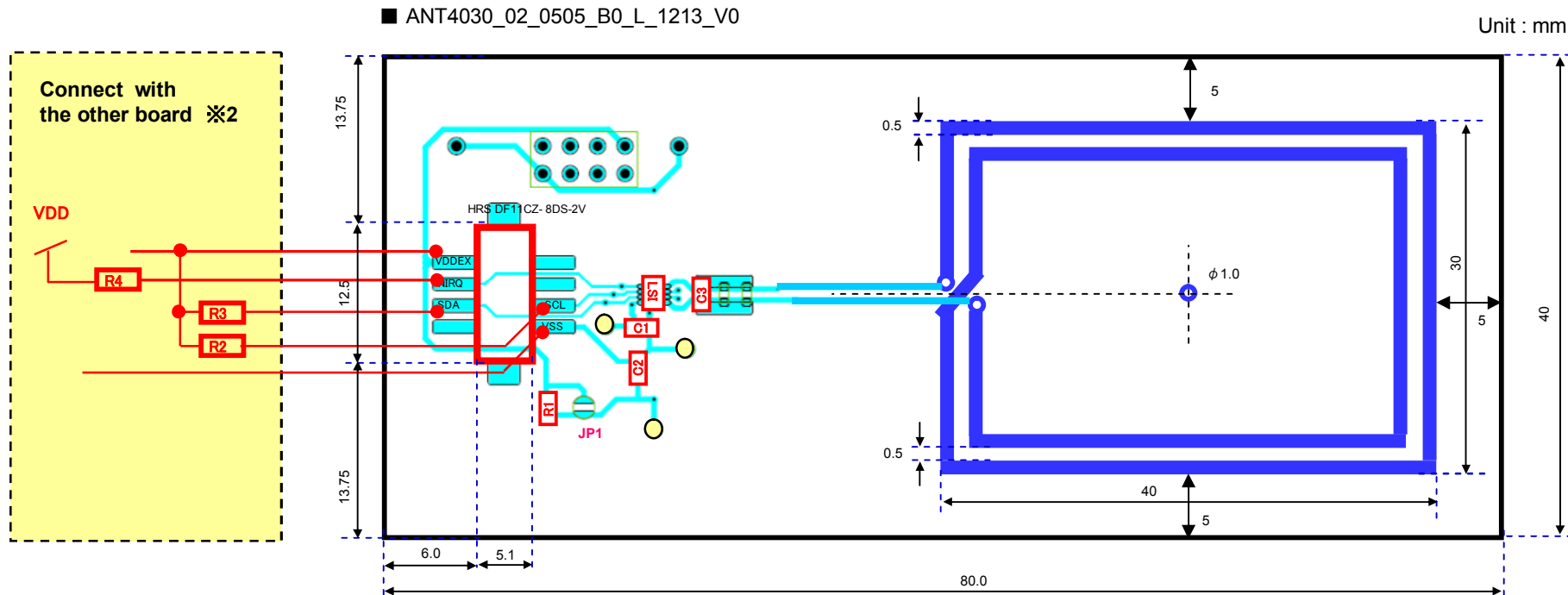
Ver. 1.0

Sep.5<sup>th</sup>,2013

Semiconductor Business Group  
Industrial Devices Company  
Panasonic Corporation



Pin No.	Name		Input/Output	IO type	Function
	MN63Y1212	MN63Y1213			
1	VB	VB	I/O	---	Coil terminal
2	N.C.	VDDEX	---	--- / Power	MN63Y1212: Open or Connect to Ground MN63Y1213: External Power Supply
3	VSS	VSS	---	GND	Ground
4	VA	VA	I/O	---	Coil terminal
5	NIRQ	NIRQ	Output	Open Drain	USE : Pull up to VDD NOT USE : Open or Connect to Ground (same as Pin No.2)
6	N.C.	SCL	--- / Input	--- / Open Drain	MN63Y1212: Open or Connect to Ground (same as Pin No.2) MN63Y1213: I2C Clock input
7	N.C.	SDA	--- / I/O	--- / Open Drain	MN63Y1212: Open or Connect to Ground (same as Pin No.2) MN63Y1213: I2C Data input/output
8	VDDA	VDDA	---	Power	Internal analog power supply (Connect a capacitor between this pin and VSS shortest as possible.)

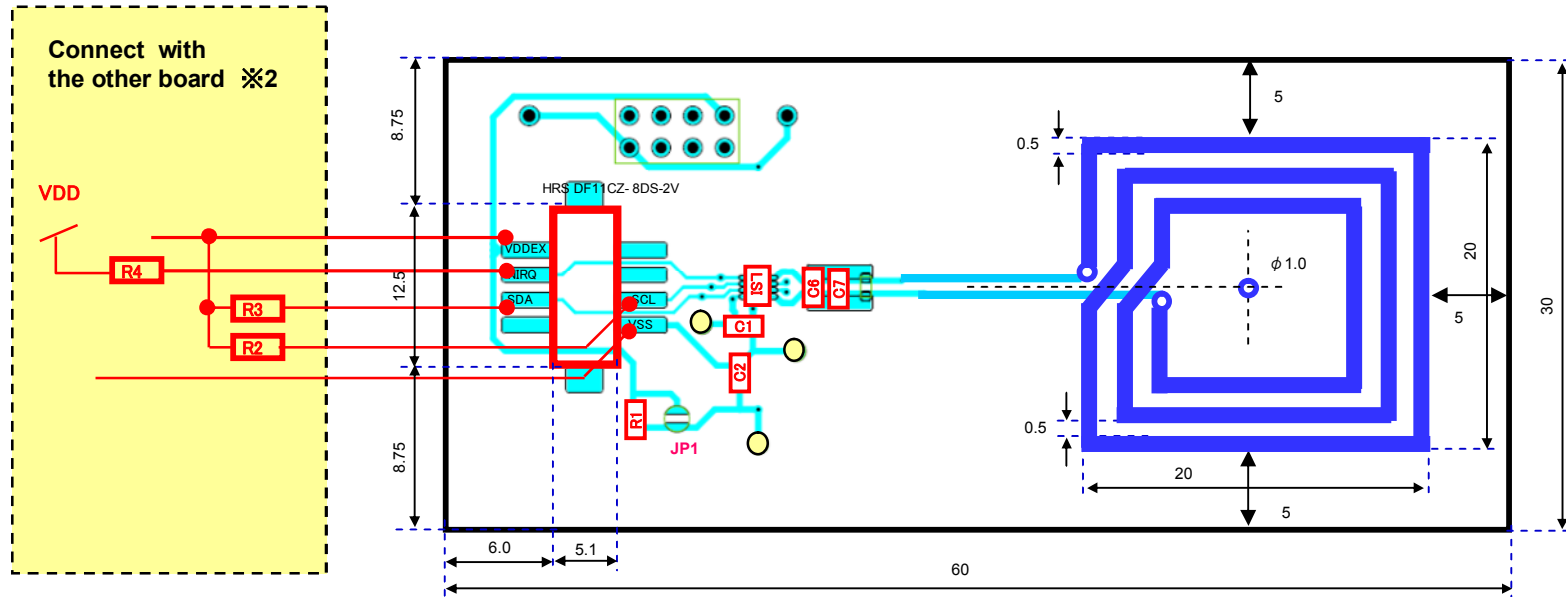


- ※ Substrate size may differ from the substrate which exists to a visitor.
- ※ I connect pulling up resistance (R,R2,R3) to the microcomputer board of our offer.

External parts	Recommended Value	Detail explanation
R2,R3	3.3kΩ	These are pull up resistor for I2C signal lines. Please choose the value considering data speed, parasitic capacitance of signal lines, and current drive performance. In our NFC tag board "ANT4030_02_0505_B0_L," it is not implemented.
R4	3.3kΩ	This is pull up resistor for interrupt signal lines. Please choose the value considering data speed, parasitic capacitance of signal lines, and current drive performance. In our NFC tag board "ANT4030_02_0505_B0_L," it is not implemented.
C1、C2	2.2μF	It is a fixed value at the capacity between the power supply for operation stabilization of the tag LSI. C2 is connected to VDDD, and C3 is connected to VDDA and C4 is connected to VDDEX.
R1	200Ω	Please set 200 ohm when use VDDEX between 2.5 to 3.6 V ( Default value ) Please set 0 ohm when use VDDEX between 1.7V to 2.5V ( Short JP1 )

■ ANT2020\_02\_0505\_B0\_L\_1213\_V0

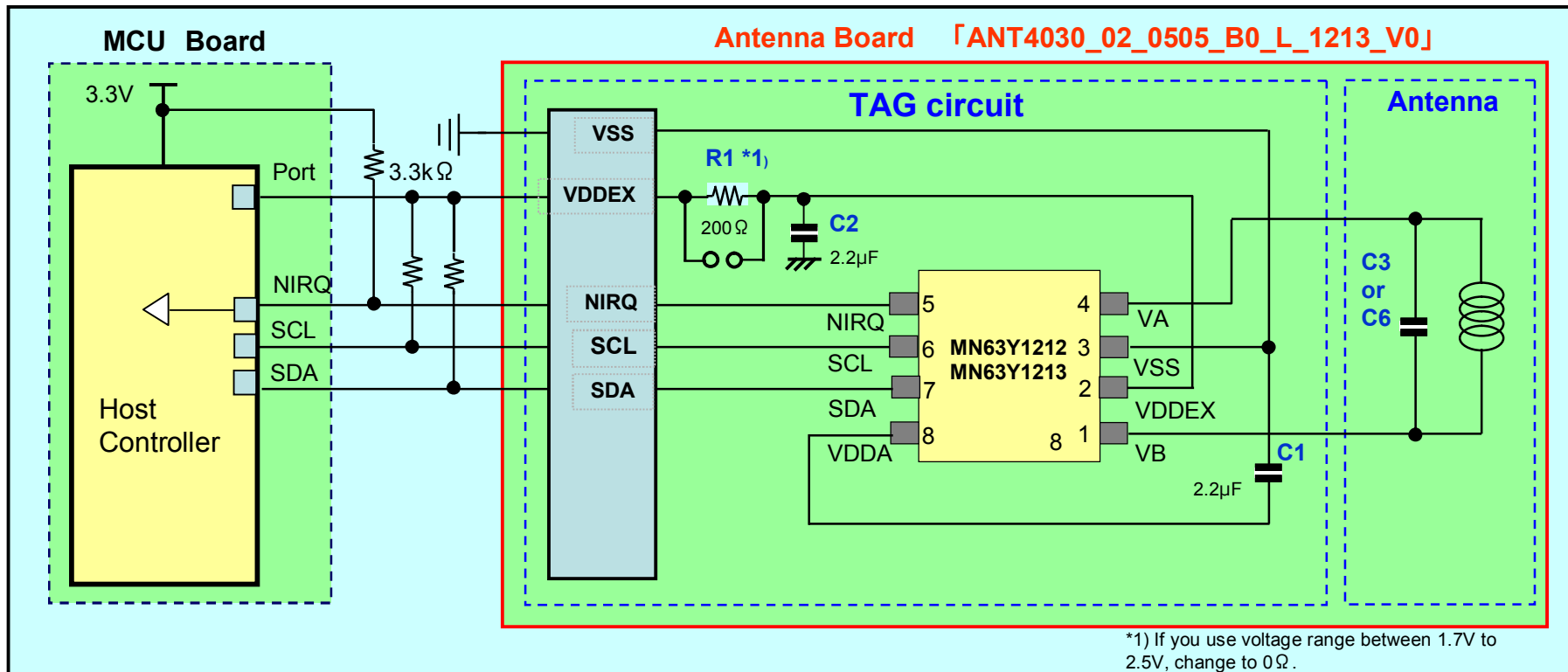
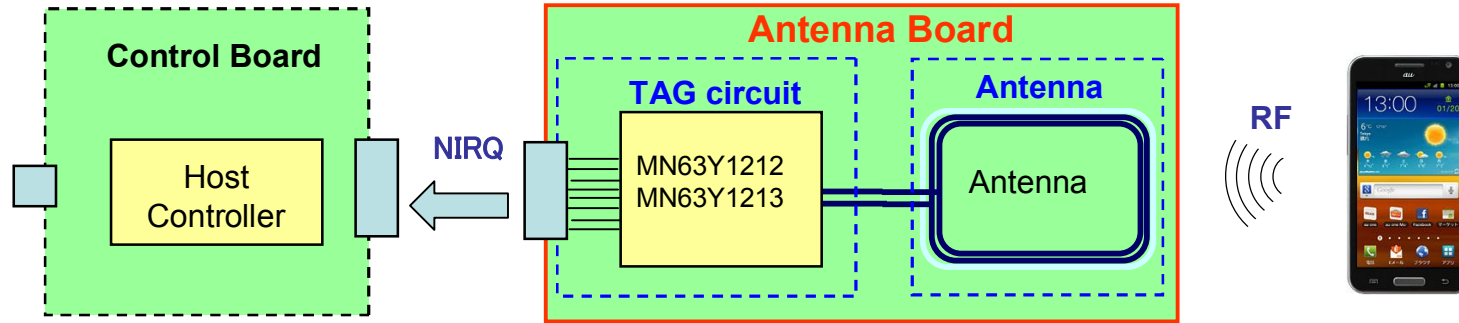
Unit: mm



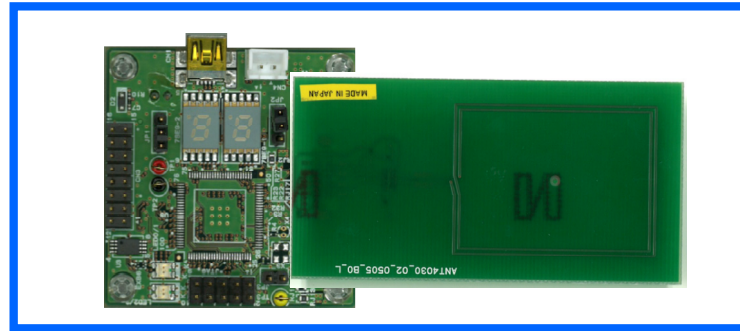
- ※ Substrate size may differ from the substrate which exists to a visitor.
- ※ I connect pulling up resistance (R,R2,R3) to the microcomputer board of our offer.

External parts	Recommended Value	Detail explanation
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C1、C2	2.2μF	It is a fixed value at the capacity between the power supply for operation stabilization of the tag LSI. C2 is connected to VDDD, and C3 is connected to VDDA and C4 is connected to VDEEX.
R1	200Ω	Please set 200 ohm when use VDEEX between 2.5 to 3.6 V ( Default value ) Please set 0 ohm when use VDEEX between 1.7V to 2.5V ( Short JP1 )

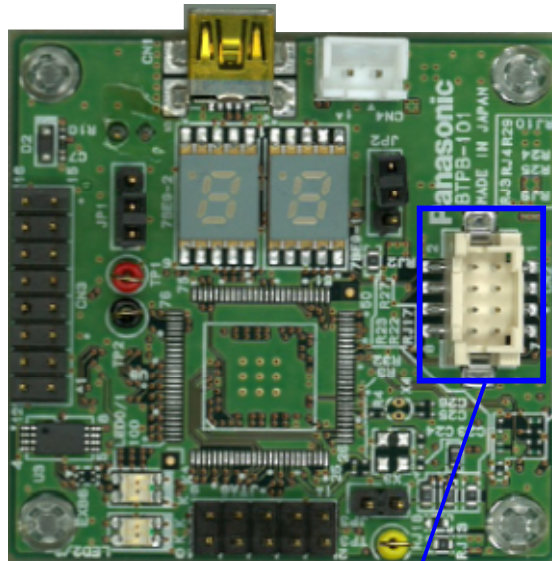
## NFC tag system constitution



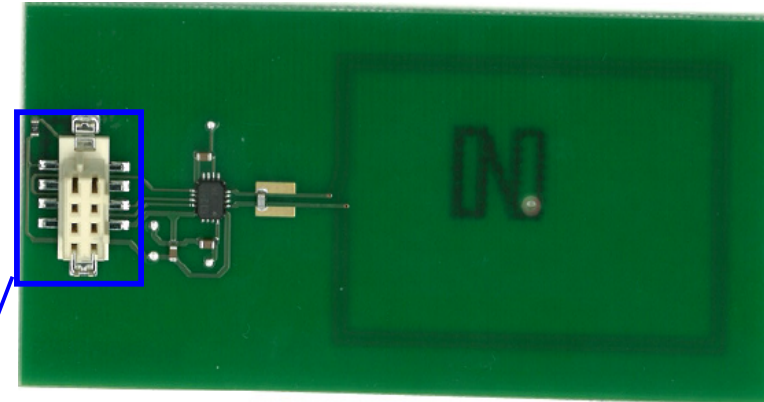
## Connection image (Top view)



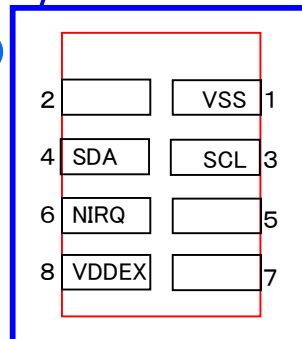
Micon board [BTPB101-B]



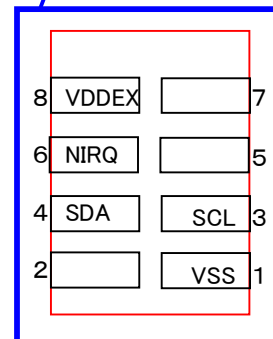
Antenna board [ANT4030\_02\_0505\_B0\_L\_1213\_V0]

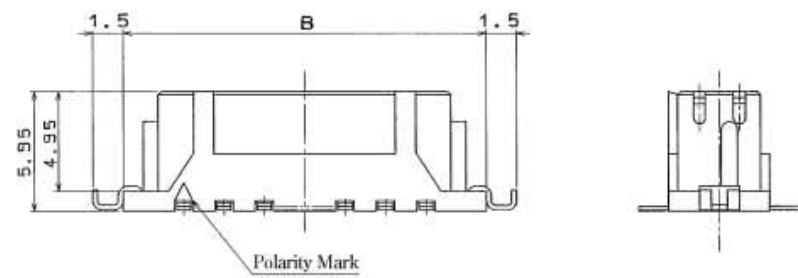
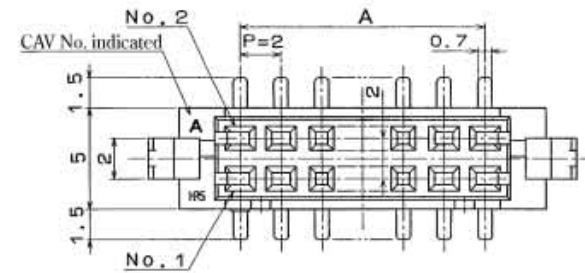
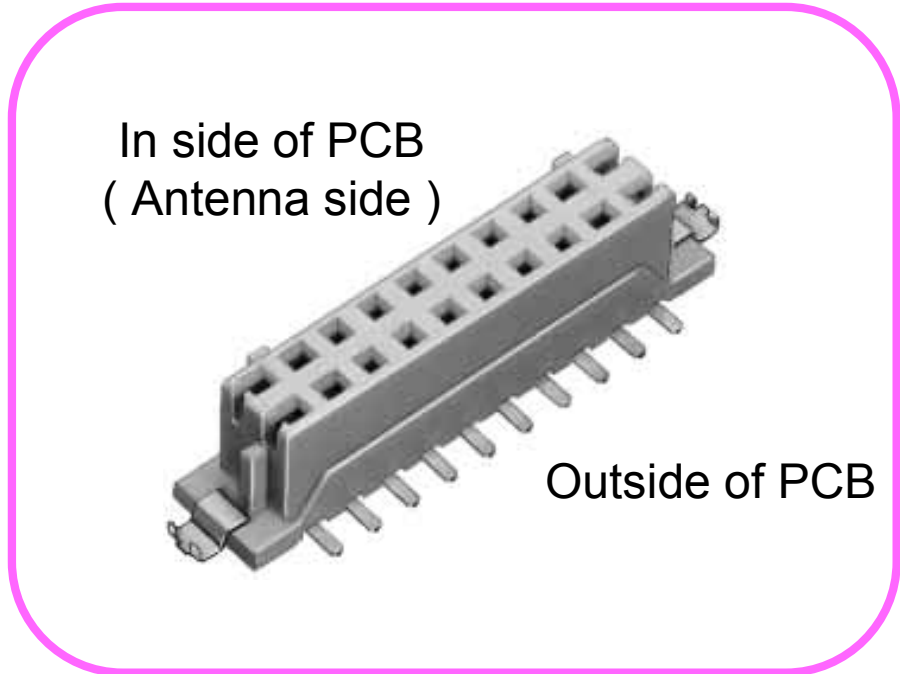


DF11GZ-8DP-2V(27)  
( Hirose Electric )



HRS DF11GZ- 8DS-2V  
( Hirose Electric )





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